

**BOND FINGER ON VIA SUBSTRATE, PROCESS OF MAKING SAME,  
PACKAGE MADE THEREBY, AND METHOD OF ASSEMBLING SAME**

**ABSTRACT OF THE DISCLOSURE**

5           A wire-bonding substrate is disclosed. The wire-bonding substrate includes  
a first wire-bond pad and a first via that is disposed directly below the first wire-  
bond pad in the in the wire-bonding substrate. A package is also disclosed that  
includes a die that is coupled to the first wire-bonding pad. The package can  
include a larger substrate that is coupled to the wire-bonding substrate through an  
10   electrical connection such as a solder ball. A process of forming the wire-bonding  
substrate is also disclosed. The process includes via formation to stop on the wire-  
bond pad. A method of assembling a microelectronic package is also disclosed that  
includes coupling the die to the wire-bond pad. A computing system is also  
disclosed that includes the wire-bonding substrate.